

# SF2316E-1

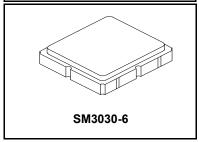
- · Low-loss 1582 MHz SAW Filter
- Designed for 50 ohm Source/Load
- Complies with Directive 2002/95/EC (RoHS)
- Operable Temperature Range -45°/125°C
- · Meets AEC-Q200 Standards

## **Absolute Maximum Ratings**



Rating	Value	Units
Input Power Level	+10	dBm
DC Voltage on any Non-ground Terminal	3	V
Operable Temperature Range	-45 to +125	°C
Operating Temperature Range	-40 to +10	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C

# 1582 MHz **SAW Filter**



#### **Electrical Characteristics**

Characteristic		Sym	Notes	Min	Тур	Max	Units
Center Frequency		f <sub>C</sub>			1582		MHz
Insertion Loss, 1565.42 to 1585.42MHz		IL			1.8	2.4	
Insertion Loss, 1574.42 to 1576.42MHz					1.6	2.2	
Insertion Loss, 1576.42 to 1597.42MHz					1.6	2.2	dB
Insertion Loss, 1597.55 to 1605.89MHz	(-40 to +85°)				2.0	2.6	
	(-40 to +105°C)				2.0	2.8	
GD Ripple, 1597.55 to 1605.89 MHz					8.5	20	ns
Amplitude Ripple, 1559 to 1606 MHz	(-40 to +85°C)				0.9	2.0	dВ
	(-40 to +105°C)				0.9	2.5	dB
VSWR, 1565.42 to 1585.42 MHz					2.0	2.2	-10
VSWR, 1597.55 to 1605.89 MHz					1.4	2.0	dB
Attenuation,							
1 to 925 MHz				32	37		
925 to 960 MHz				32	37		1
1427 to1453 MHz				35	45		
1453 to 1501 MHz				35	46		
1501 to 1525 MHz				30	37		
1626 to 1660 MHz				30	43		dB
1710 to 1785 MHz				35	40		
1850 to 1910 MHz				35	41		
1920 to 1980 MHz				35	42		
2110 to 2170 MHz				35	44		
2400 to 2500 MHz				40	46		
2500 to 2570 MHz				40	44		
Case Style			SN	/ID 3.0 x 3.0 n	nm Nominal Fo	otprint	
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator				A80	, YWWS		

# CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to

So  $\Omega$  and measured with 50  $\Omega$  network analyzer.

Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, fc.

Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance

Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.

"LRIP" or "L" after the part number indicates "low rate initial production" and "ENG" or "E" indicates "engineering prototypes."

The design, manufacturing process, and specifications of this filter are subject to change.

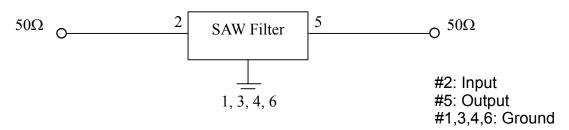
Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.

US and international patents may apply.

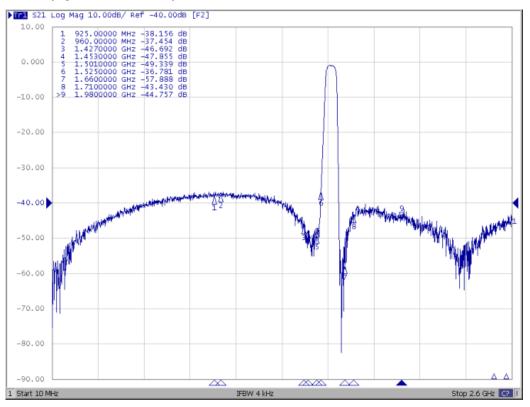
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### **Measurement Circuit:**

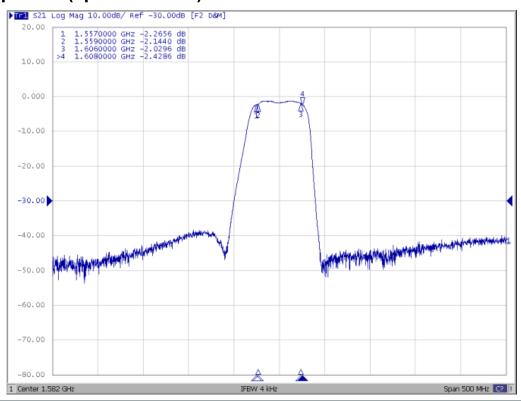
HP Network analyzer



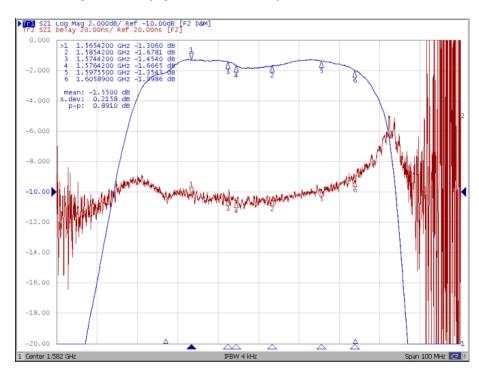
# Frequency Characteristics: S21 response: (span 2.6 GHz)



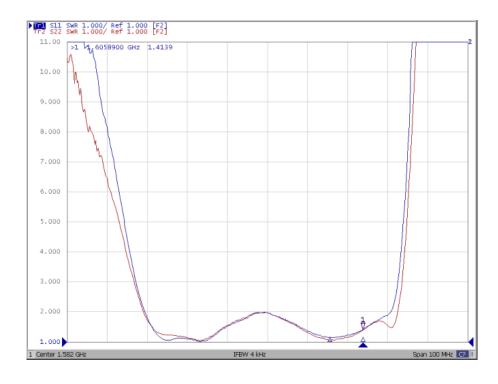
# S21 response: (span 500 MHz)



# S21 response: (span 100 MHz)

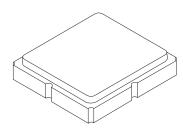


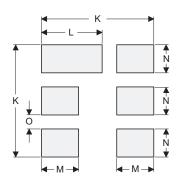
# S11 and S22VSWR: (span 100 MHz)



# SM3030-6 Ceramic 6-Terminal Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint

# **Case and PCB Footprint Dimensions**





**PCB Footprint Top View** 

Dimension	mm			Inches			
Dimension	Min	Nom	Max	Min	Nom	Max	
Α	2.87	3.00	3.13	0.113	0.118	0.123	
В	2.87	3.00	3.13	0.113	0.118	0.123	
С	1.12	1.25	1.38	0.044	0.049	0.054	
D	0.77	0.90	1.03	0.030	0.035	0.040	
E	2.67	2.80	2.93	0.105	0.110	0.115	
F	1.47	1.60	1.73	0.058	0.063	0.068	
G	0.72	0.85	0.98	0.028	0.033	0.038	
Н	1.37	1.50	1.63	0.054	0.059	0.064	
I	0.47	0.60	0.73	0.019	0.024	0.029	
J	1.17	1.30	1.43	0.046	0.051	0.056	
K		3.20			0.126		
L		1.70			0.067		
М		1.05			0.041		
N		0.81			0.032		
0		0.38			0.015		

### **Case Materials**

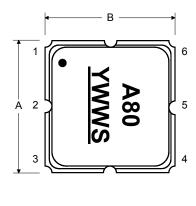
← D →

Materials				
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel			
Lid Plating	2.0 to 3.0 µm Nickel			
Body	Al <sub>2</sub> O <sub>3</sub> Ceramic			
Pb Free				

### **Electrical Connections**

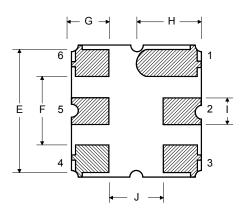
Connection	Terminals
Input	2
Output	5
Case Ground	All others

# **TOP VIEW**

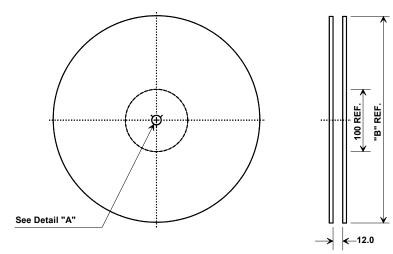




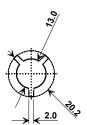
## **BOTTOM VIEW**



## **Tape and Reel Specifications**



•	'B"	Quantity Per Reel
Inches	millimeters	Quantity Fer Reer
7	178	500
13	330	3000



### **COMPONENT ORIENTATION and DIMENSIONS**

Carrier Tape Dimensions				
Ao	3.35 mm			
Во	3.35 mm			
Ko	1.40 mm			
Pitch	8.0 mm			
W	12.0 mm			

